

6367254 MOTOROLA SC (XSTRS/R F)

96D 81076 D

MOTOROLA SEMICONDUCTOR TECHNICAL DATA

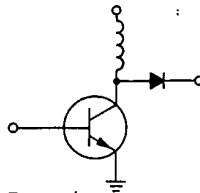
T-33-13
MJ13080
MJ13081

Designer's Data Sheet

SWITCHMODE II SERIES NPN SILICON POWER TRANSISTORS

The MJ13080 and MJ13081 transistors are designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line-operated switch-mode applications such as:

- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls
- Deflection Circuits



Fast Turn-Off Times

- 100 ns Inductive Fall Time @ 25°C (Typ)
- 150 ns Inductive Crossover Time @ 25°C (Typ)
- 400 ns Inductive Storage Time @ 25°C (Typ)

Operating Temperature Range -65 to +200°C

100°C Performance Specified for:
Reverse-Biased SOA with Inductive Loads
Switching Times with Inductive Loads
Saturation Voltages
Leakage Currents

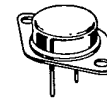
8 AMPERE

NPN SILICON POWER TRANSISTORS

400 AND 450 VOLTS
150 WATTS

Designer's Data for "Worst Case" Conditions

The Designer's Data Sheet permits the design of most circuits entirely from the information presented. Limit data — representing device characteristics boundaries — are given to facilitate "worst case" design.



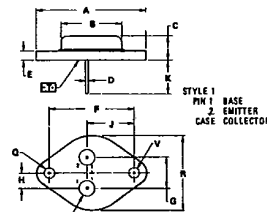
MAXIMUM RATINGS

Rating	Symbol	MJ13080	MJ13081	Unit
Collector-Emitter Voltage	V _{CEO}	400	450	Vdc
Collector-Emitter Voltage	V _{CEV}	650	750	Vdc
Emitter Base Voltage	V _{EB}	6.0		Vdc
Collector Current — Continuous	I _C	8.0		Adc
— Peak (1)	I _{CM}	12		
Base Current — Continuous	I _B	3.0		Adc
— Peak (1)	I _{BM}	6.0		
Total Power Dissipation @ T _C = 25°C	P _D	150		Watts
Derate above 25°C @ T _C = 100°C		85.5		W/°C
		0.86		
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +200		°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R _{θJC}	1.17	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	T _L	275	°C

(1) Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.



- NOTES:
1. DIMENSIONS D AND V ARE DATUMS.
2. [] IS SEATING PLANE AND DATUM FOR MOUNTING HOLE D.
3. POSITIONAL TOLERANCE FOR MOUNTING HOLE D.
4. DIMENSIONS AND TOLERANCES PER ANSI Y14.5 1913

MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX
A	3.57	—	0.140	—
B	21.65	—	0.852	—
C	6.35	7.62	0.250	0.300
D	0.91	1.09	0.035	0.043
E	1.27	1.27	0.050	0.050
F	22.15 BSC	—	0.871 BSC	—
G	12.92 BSC	—	0.509 BSC	—
H	3.95 BSC	—	0.155 BSC	—
J	16.83 BSC	—	0.663 BSC	—
K	11.18	12.19	0.440	0.479
L	3.81	4.19	0.150	0.165
M	26.41	—	1.036	—
N	4.83	5.33	0.190	0.210
V	3.81	4.19	0.150	0.165

CASE 1-05
TO-204AA



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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit		
OFF CHARACTERISTICS (1)							
Collector-Emitter Sustaining Voltage (Table 1) (I _C = 100 mA, I _B = 0)	MJ13080 MJ13081	V _{CEO(sus)}	400 450	— —	V _{dc}		
Collector Cutoff Current (V _{CEV} = Rated Value, V _{BE(off)} = 1.5 V _{dc}) (V _{CEV} = Rated Value, V _{BE(off)} = 1.5 V _{dc} , T _C = 100°C)		I _{CEV}	— —	0.5 2.5	mAdc		
Collector Cutoff Current (V _{CE} = Rated V _{CEV} , R _{BE} = 50 Ω, T _C = 100°C)		I _{CER}	—	3.0	mAdc		
Emitter Cutoff Current (V _{EB} = 6.0 V _{dc} , I _C = 0)		I _{EBO}	—	1.0	mAdc		
SECOND BREAKDOWN							
Second Breakdown Collector Current with Base Forward Biased	I _{S/b}	See Figure 12					
Clamped Inductive SOA with Base Reverse Biased	RBSOA	See Figure 13					
ON CHARACTERISTICS (1)							
DC Current Gain (I _C = 5.0 Adc, V _{CE} = 3.0 V _{dc})	h _{FE}	8.0	—	—	—		
Collector-Emitter Saturation Voltage (I _C = 5.0 Adc, I _B = 1.0 Adc) (I _C = 8.0 Adc, I _B = 1.6 Adc) (I _C = 5.0 Adc, I _B = 1.0 Adc, T _C = 100°C)	V _{CE(sat)}	— — —	— — —	1.0 3.0 2.0	V _{dc}		
Base-Emitter Saturation Voltage (I _C = 5.0 Adc, I _B = 1.0 Adc) (I _C = 5.0 Adc, I _B = 1.0 Adc, T _C = 100°C)	V _{BE(sat)}	— —	— —	1.5 1.5	V _{dc}		
DYNAMIC CHARACTERISTICS							
Output Capacitance (V _{CB} = 10 V _{dc} , I _E = 0, f _{test} = 1.0 kHz)	C _{ob}	—	—	300	pF		
SWITCHING CHARACTERISTICS							
Resistive Load (Table 1)							
Delay Time	(V _{CC} = 250 V _{dc} , I _C = 5.0 Adc, I _{B1} = 0.7 Adc, t _p = 30 μs, Duty Cycle ≤ 2%, V _{BE(off)} = 5.0 V _{dc})	t _d	—	0.025	0.05	μs	
Rise Time		t _r	—	0.10	0.50		
Storage Time		t _s	—	0.50	1.50		
Fall Time		t _f	—	0.15	0.50		
Inductive Load, Clamped (Table 1)							
Storage Time	(I _{C(pk)} = 5.0 A, I _{B1} = 0.7 Adc, V _{BE(off)} = 5.0 V _{dc} , V _{CE(pk)} = 250 V)	(T _J = 100°C)	t _{sv}	—	0.75	2.20	μs
Crossover Time			t _c	—	0.22	0.40	
Fall Time		t _{fi}	—	0.175	0.35		
Storage Time		(T _J = 25°C)	t _{sv}	—	0.40	—	
Crossover Time			t _c	—	0.15	—	
Fall Time			t _{fi}	—	0.10	—	

(1) Pulse Test: PW - 300 μs, Duty Cycle ≤ 2%.

$$\beta_f = \frac{I_C}{I_B}$$



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TYPICAL ELECTRICAL CHARACTERISTICS

FIGURE 1 — DC CURRENT GAIN

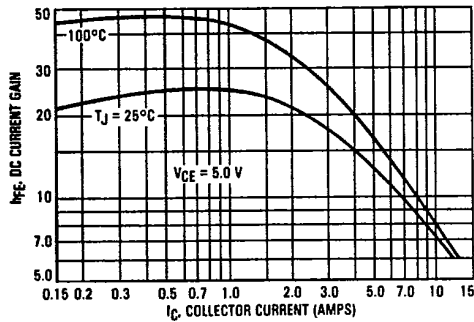


FIGURE 2 — COLLECTOR SATURATION REGION

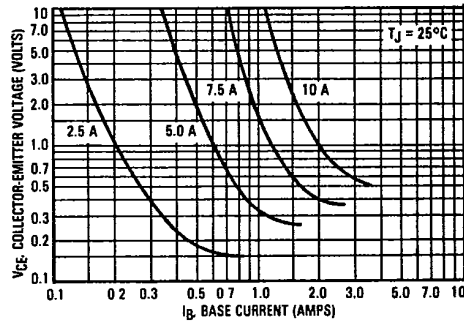


FIGURE 3 — COLLECTOR-EMITTER SATURATION VOLTAGE

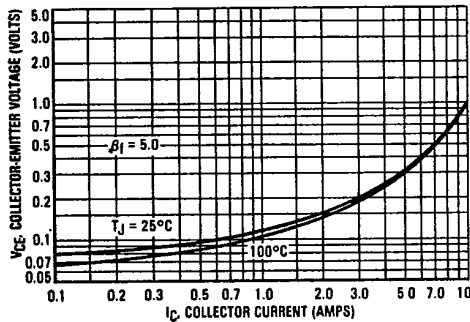


FIGURE 4 — BASE-EMITTER VOLTAGE

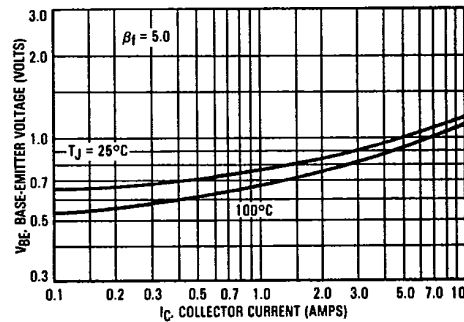


FIGURE 5 — COLLECTOR CUTOFF REGION

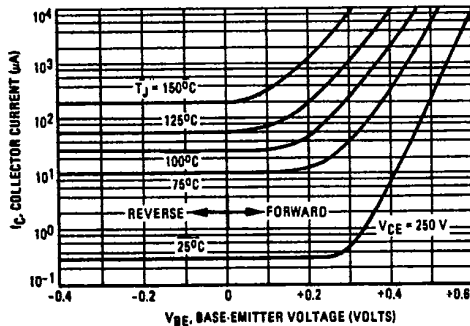
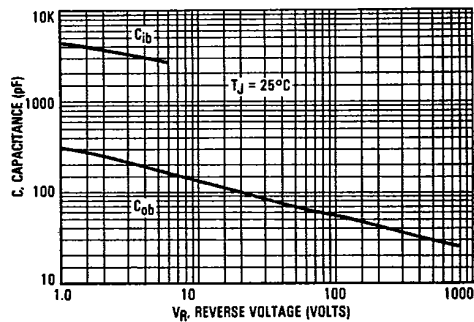


FIGURE 6 — CAPACITANCE



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TABLE 1 - TEST CONDITIONS FOR DYNAMIC PERFORMANCE

	V _{CE0(sus)}	RBSOA AND INDUCTIVE SWITCHING	RESISTIVE SWITCHING
INPUT CONDITIONS	<p>PW Varied to Attain I_C = 100 mA</p>	<p>Adjust R1 to obtain I_{B1} For switching and R_{BSOA}, R2 = 0 For V_{CE0(sus)}, R2 = ∞</p>	<p>TURN ON TIME I_{B1} adjusted to obtain the forced h_{FE} desired</p> <p>TURN OFF TIME Use inductive switching driver as the input to the resistive test circuit</p>
CIRCUIT VALUES	L _{coil} = 80 mH V _{CC} = 10 V R _{coil} = 0.7 Ω	L _{coil} = 180 μH R _{coil} = 0.05 Ω V _{CC} = 20 V V _{clamp} = 250 V R _B adjusted to attain desired I _{B1}	V _{CC} = 250 V R _L = 50 Ω Pulse Width = 30 μs
TEST CIRCUITS	<p>INDUCTIVE TEST CIRCUIT</p> <p>OUTPUT WAVEFORMS</p> <p>RESISTIVE TEST CIRCUIT</p> <p>t₁ Adjusted to Obtain I_C</p> $t_1 \approx \frac{L_{coil}(I_{Cpk})}{V_{CC}}$ $t_2 \approx \frac{L_{coil}(I_{Cpk})}{V_{clamp}}$ <p>Test Equipment Scope - Tektronix 475 or Equivalent</p>		

FIGURE 7 - INDUCTIVE SWITCHING MEASUREMENTS

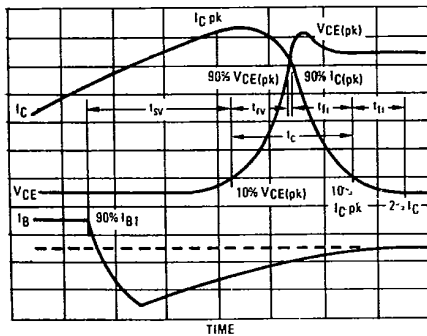
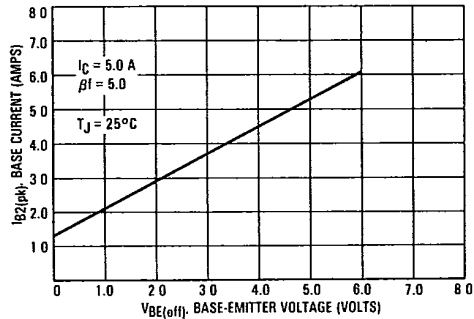


FIGURE 8 - PEAK REVERSE CURRENT



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SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

- t_{sv} = Voltage Storage Time, 90% I_{B1} to 10% V_{clamp}
- t_{rv} = Voltage Rise Time, 10–90% V_{clamp}
- t_{fi} = Current Fall Time, 90–10% I_C
- t_{ti} = Current Tail, 10–2% I_C
- t_c = Crossover Time, 10% V_{clamp} to 10% I_C

An enlarged portion of the inductive switching waveforms

is shown in Figure 7 to aid in the visual identity of these terms.

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN-222:

$$P_{SWT} = 1/2 V_{CC} I_C (t_c) f$$

In general, $t_{rv} + t_{fi} \approx t_c$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_c and t_{sv}) which are guaranteed at 100°C.

INDUCTIVE SWITCHING

FIGURE 9 — STORAGE TIME

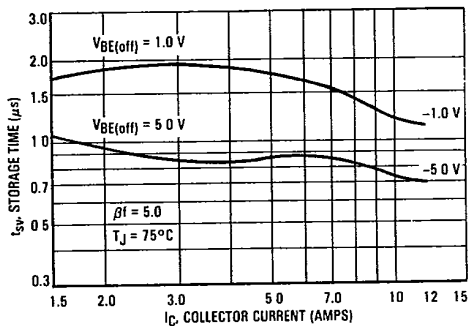


FIGURE 10 — CROSSOVER AND FALL TIMES

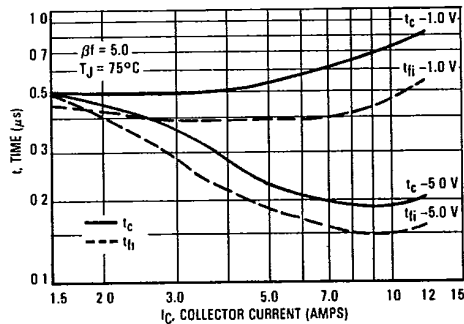
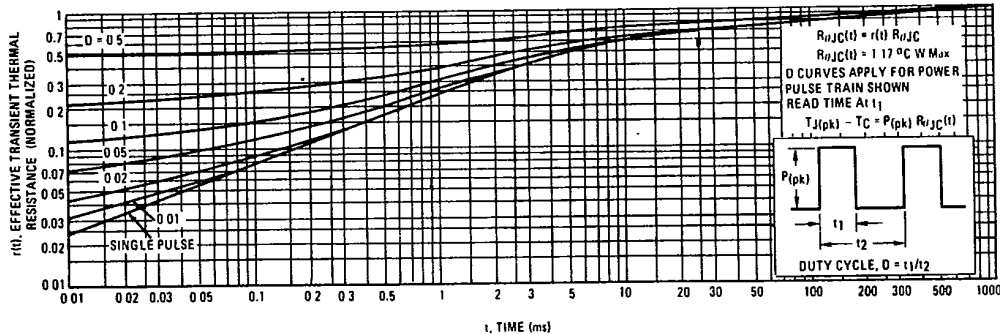


FIGURE 11 — THERMAL RESPONSE



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The Safe Operating Area figures shown in Figures 12 and 13 are specified for these devices under the test conditions shown.

FIGURE 12 — FORWARD BIAS SAFE OPERATING AREA

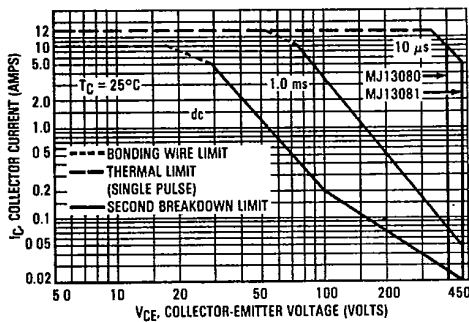


FIGURE 13 — REVERSE BIAS SAFE OPERATING AREA

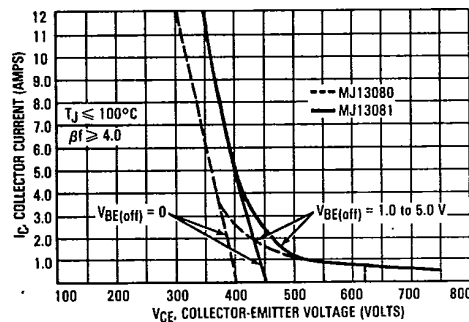
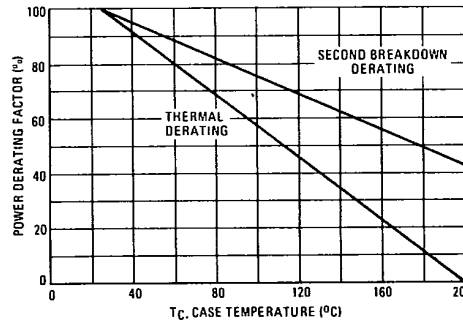


FIGURE 14 — POWER DERATING



SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate IC-VCE limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on TC = 25°C; TJ(pk) is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when TC ≥ 25°C. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 12 may be found at any case temperature by using the appropriate curve on Figure 14.

TJ(pk) may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current conditions during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 13 gives RBSOA characteristics.

